Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature .....–65°C to +150°C

Ambient Temperature with Power Applied.....–55°C to +125°C

Supply Voltage to Ground Potential (Pin 24 to Pin 12).....–0.5V to +7.0V

DC Voltage Applied to Outputs in High Z State[1] ..... –0.5V to V_{CC} + 0.5V

DC Input Voltage[1]..... –0.5V to V_{CC} + 0.5V

Output Current into Outputs (LOW)..... 20 mA

Static Discharge Voltage ..... >2001V (per MIL-STD-883, Method 3015)

Latch-Up Current..... >200 mA

Operating Range

Range	Ambient Temperature	V_{CC}
Commercial	0°C to +70°C	5V ± 10%

Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions	7C197-12		7C197-15		Unit
			Min.	Max.	Min.	Max.	
V_{OH}	Output HIGH Voltage	V_{CC} = Min., I_{OH} = –4.0 mA	2.4		2.4		V
V_{OL}	Output LOW Voltage	V_{CC} = Min. I_{OL}=12.0 mA		0.4		0.4	V
V_{IH}	Input HIGH Voltage		2.2	V_{CC} + 0.3V	2.2	V_{CC} +0.3V	V
V_{IL}	Input LOW Voltage[1]		–0.5	0.8	–0.5	0.8	V
I_{IX}	Input Load Current	GND ≤ V_I ≤ V_{CC}	–5	+5	–5	+5	µA
I_{OZ}	Output Leakage Current	GND ≤ V_O ≤ V_{CC}, Output Disabled	–5	+5	–5	+5	µA
I_{OS}	Output Short Circuit Current[2]	V_{CC} = Max., V_{OUT} = GND		–300		–300	mA
I_{CC}	V_{CC} Operating Supply Current	V_{CC} = Max., I_{OUT} = 0 mA, f = f_{MAX} = $1/t_{RC}$		150		140	mA
I_{SB1}	Automatic $\overline{CE}$ Power-Down Current—TTL Inputs[3]	Max. V_{CC}, $\overline{CE}$ ≥ V_{IH}, V_{IN} ≥ V_{IH} or V_{IN} ≤ V_{IL}, f = f_{MAX}		30		30	mA
I_{SB2}	Automatic $\overline{CE}$ Power-Down Current—CMOS Inputs[3]	Max. V_{CC}, $\overline{CE}$ ≥ V_{CC} – 0.3V, V_{IN} ≥ V_{CC} – 0.3V or V_{IN} < 0.3V		10		10	mA

Notes:

1. $V_{(min.)}$ = –2.0V for pulse durations of less than 20 ns.
2. Not more than one output should be shorted at one time. Duration of the short circuit should not exceed 30 seconds.
3. A pull-up resistor to V_{CC} on the $\overline{CE}$ input is required to keep the device deselected during V_{CC} power-up, otherwise I_{SB} will exceed values given.

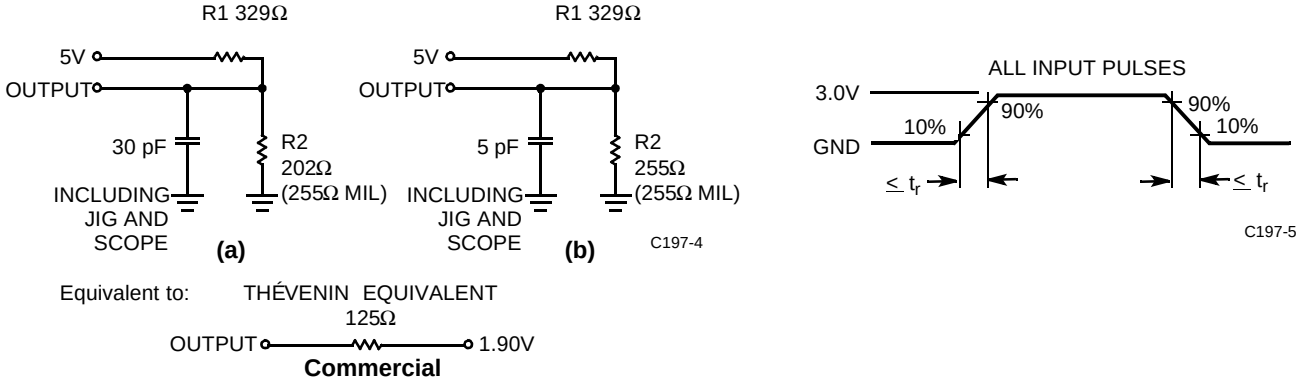
Electrical Characteristics Over the Operating Range (continued)

Parameter	Description	Test Conditions	7C197-20 Min.	7C197-20 Max.	7C197-25, 35, 45 Min.	7C197-25, 35, 45 Max.	Unit
V_{OH}	Output HIGH Voltage	V_{CC} = Min., I_{OH} = –4.0 mA	2.4		2.4		V
V_{OL}	Output LOW Voltage	V_{CC} = Min. I_{OL}=12.0mA		0.4		0.4	V
V_{IH}	Input HIGH Voltage		2.2	V_{CC} + 0.3V	2.2	V_{CC} + 0.3V	V
V_{IL}	Input LOW Voltage[1]		–0.5	0.8	–0.5	0.8	V
I_{IX}	Input Load Current	GND ≤ V_I ≤ V_{CC}	–5	+5	–5	+5	µA
I_{OZ}	Output Leakage Current	GND ≤ V_O ≤ V_{CC}, Output Disabled	–5	+5	–5	+5	µA
I_{OS}	Output Short Circuit Current[2]	V_{CC} = Max., V_{OUT} = GND		–300		–300	mA
I_{CC}	V_{CC} Operating Supply Current	V_{CC} = Max., I_{OUT} = 0 mA, f = f_{MAX} = $1/t_{RC}$		135		95	mA
I_{SB1}	Automatic $\overline{CE}$ Power Down Current—TTL Inputs[3]	Max. V_{CC}, $\overline{CE}$ ≥ V_{IH}, V_{IN} ≥ V_{IH} or V_{IN} ≤ V_{IL}, f = f_{MAX}		30		30	mA
I_{SB2}	Automatic $\overline{CE}$ Power-Down Current—CMOS Inputs[3]	Max. V_{CC}, $\overline{CE}$ ≥ V_{CC} – 0.3V, V_{IN} ≥ V_{CC} – 0.3V or V_{IN} < 0.3V		15		15	mA

Capacitance[4]

Parameter	Description	Test Conditions	Max.	Unit
C_{IN}	Input Capacitance	T_A = 25°C, f = 1 MHz, V_{CC} = 5.0V	8	pF
C_{OUT}	Output Capacitance		10	pF

AC Test Loads and Waveforms[5]



Notes:

4. Tested initially and after any design or process changes that may affect these parameters.
5. t_r = ≤ 3 ns for the -12 and -15 speeds. t_r = ≤ 5 ns for the -20 and slower speeds.

Switching Characteristics Over the Operating Range[6]

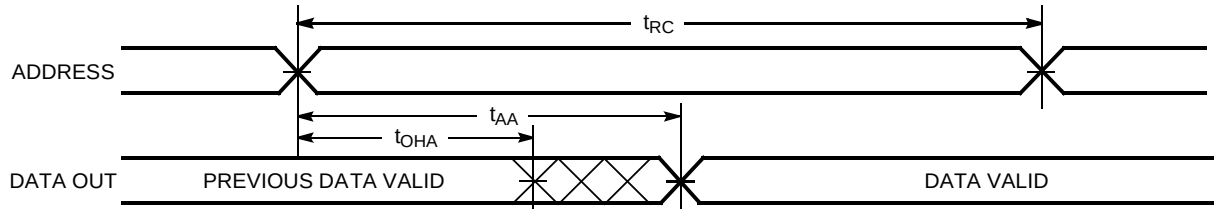
Parameter	Description	7C197-12		7C197-15		7C197-20		7C197-25		7C197-35		7C197-45		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
READ CYCLE														
t_{RC}	Read Cycle Time	12		15		20		25		35		45		ns
t_{AA}	Address to Data Valid		12		15		20		25		35		45	ns
t_{OHA}	Output Hold from Address Change	3		3		3		3		3		3		ns
t_{ACE}	$\overline{CE}$ LOW to Data Valid		12		15		20		25		35		45	ns
t_{LZCE}	$\overline{CE}$ LOW to Low Z[7]	3		3		3		3		3		3		ns
t_{HZCE}	$\overline{CE}$ HIGH to High Z[7, 8]		5		7	0	9	0	11	0	15	0	15	ns
t_{PU}	$\overline{CE}$ LOW to Power-Up	0		0		0		0		0		0		ns
t_{PD}	$\overline{CE}$ HIGH to Power-Down		12		15		20		20		25		30	ns
WRITE CYCLE[9]														
t_{WC}	Write Cycle Time	12		15		20		25		35		45		ns
t_{SCE}	$\overline{CE}$ LOW to Write End	9		10		15		20		30		40		ns
t_{AW}	Address Set-Up to Write End	9		10		15		20		30		40		ns
t_{HA}	Address Hold from Write End	0		0		0		0		0		0		ns
t_{SA}	Address Set-Up to Write Start	0		0		0		0		0		0		ns
t_{PWE}	$\overline{WE}$ Pulse Width	8		9		15		20		25		30		ns
t_{SD}	Data Set-Up to Write End	8		9		10		15		17		20		ns
t_{HD}	Data Hold from Write End	0		0		0		0		0		0		ns
t_{LZWE}	$\overline{WE}$ HIGH to Low Z[7]	2		2		3		3		3		3		ns
t_{HZWE}	$\overline{WE}$ LOW to High Z[7,8]		7		7	0	10	0	11	0	15	0	15	ns

Notes:

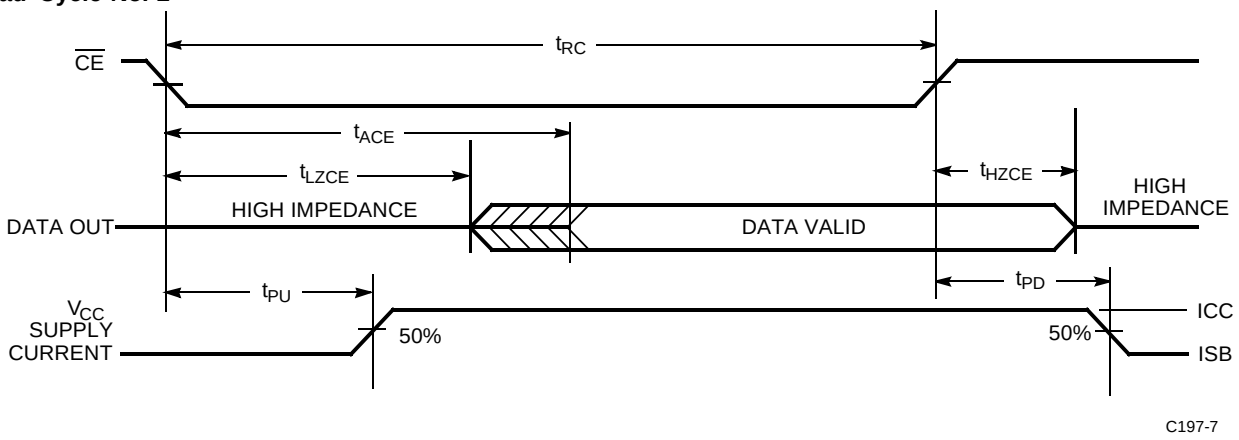
6. Test conditions assume signal transition time of 3 ns or less for -12 and -15 speeds and 5 ns or less for -20 and slower speeds, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified I_{OL}/I_{OH} and 30-pF load capacitance.
7. At any given temperature and voltage condition, t_{HZCE} is less than t_{LZCE} and t_{HZWE} is less than t_{LZWE} for any given device.
8. t_{HZCE} and t_{HZWE} are specified with C_L = 5 pF as in part (b) in AC Test Loads and Waveforms. Transition is measured ±500 mV from steady-state voltage.
9. The internal write time of the memory is defined by the overlap of $\overline{CE}$ LOW and $\overline{WE}$ LOW. Both signals must be LOW to initiate a write and either signal can terminate a write by going HIGH. The data input set-up and hold timing should be referenced to the rising edge of the signal that terminates the write.

Switching Waveforms

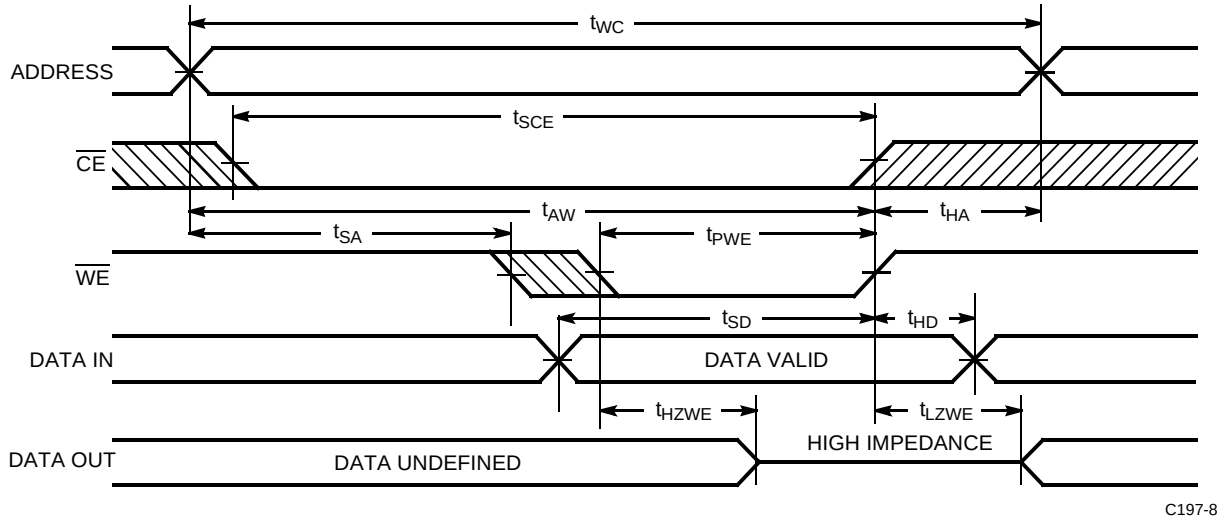
Read Cycle No. 1 [10, 11]



Read Cycle No. 2 [10]



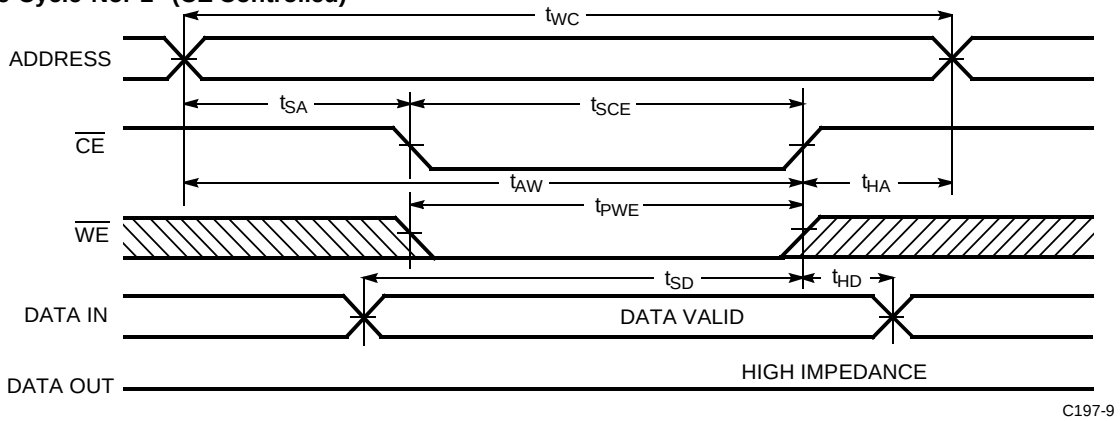
Write Cycle No. 1 (WE Controlled) [9]



Notes:
10. $\overline{WE}$ is HIGH for read cycle.
11. Device is continuously selected, $\overline{CE} = V_{IL}$.

Switching Waveforms (continued)

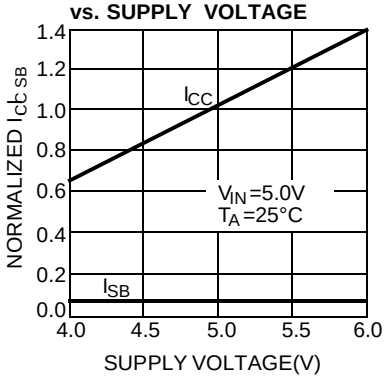
Write Cycle No. 2 ($\overline{CE}$ Controlled) [9, 12]



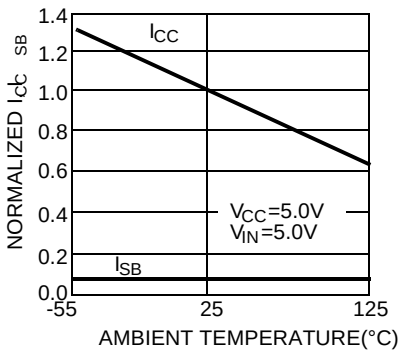
Note:
12. If $\overline{CE}$ goes HIGH simultaneously with $\overline{WE}$ HIGH, the output remains in a high-impedance state.

Typical DC and AC Characteristics

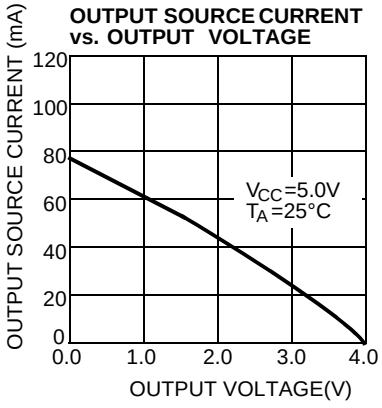
NORMALIZED SUPPLY CURRENT vs. SUPPLY VOLTAGE



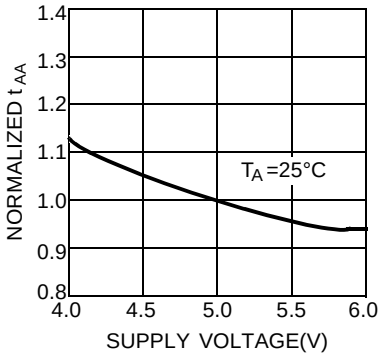
NORMALIZED SUPPLY CURRENT vs. AMBIENT TEMPERATURE



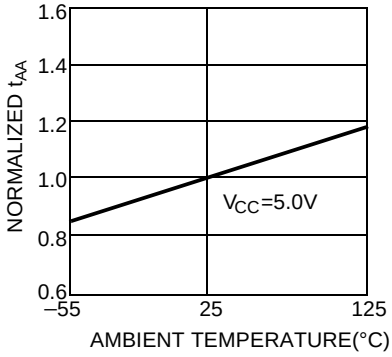
OUTPUT SOURCE CURRENT vs. OUTPUT VOLTAGE



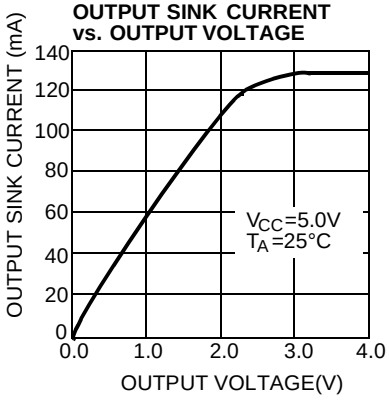
NORMALIZED ACCESS TIME vs. SUPPLY VOLTAGE



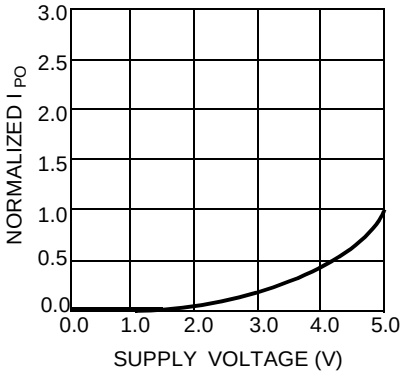
NORMALIZED ACCESS TIME vs. AMBIENT TEMPERATURE



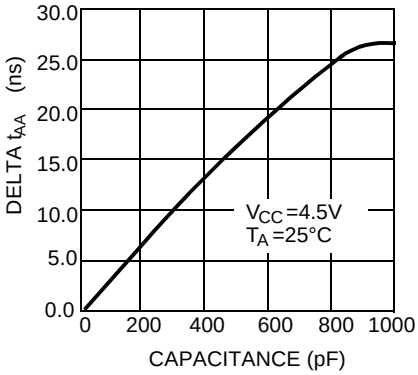
OUTPUT SINK CURRENT vs. OUTPUT VOLTAGE



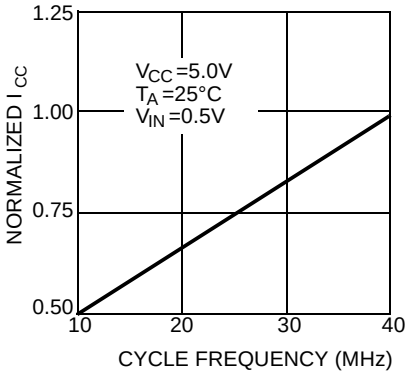
TYPICAL POWER-ON CURRENT vs. SUPPLY VOLTAGE



TYPICAL ACCESS TIME CHANGE vs. OUTPUT LOADING



NORMALIZED I_{CC} vs. CYCLE TIME



CY7C197 Truth Table

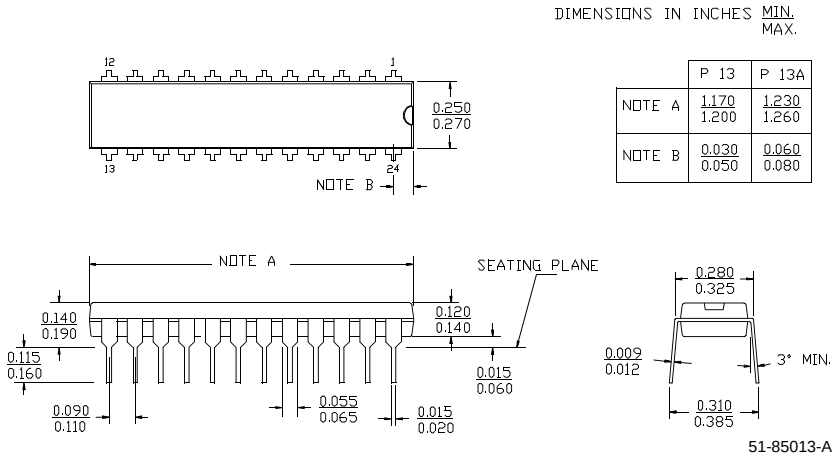
$\overline{CE}$	$\overline{WE}$	Input/Output	Mode
H	X	High Z	Deselect/Power-Down
L	H	Data Out	Read
L	L	Data In	Write

Ordering Information

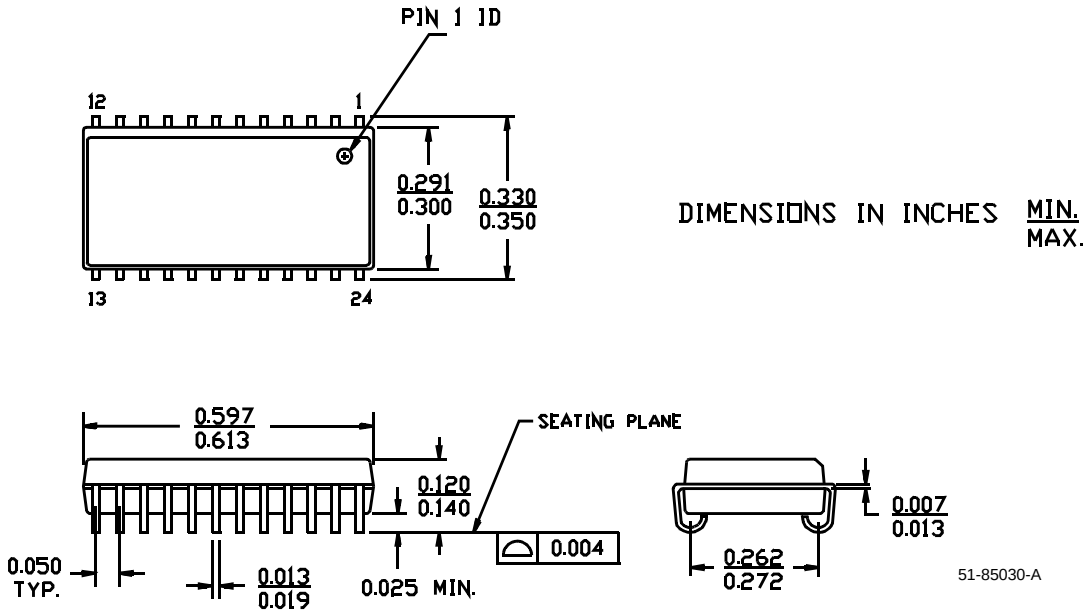
Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
12	CY7C197-12PC	P13	24-Lead (300-Mil) Molded DIP	Commercial
	CY7C197-12VC	V13	24-Lead Molded SOJ	
15	CY7C197-15PC	P13	24-Lead (300-Mil) Molded DIP	Commercial
	CY7C197-15VC	V13	24-Lead Molded SOJ	
20	CY7C197-20PC	P13	24-Lead (300-Mil) Molded DIP	Commercial
	CY7C197-20VC	V13	24-Lead Molded SOJ	
25	CY7C197-25PC	P13	24-Lead (300-Mil) Molded DIP	Commercial
	CY7C197-25VC	V13	24-Lead Molded SOJ	
35	CY7C197-35PC	P13	24-Lead (300-Mil) Molded DIP	Commercial
	CY7C197-35VC	V13	24-Lead Molded SOJ	
45	CY7C197-45PC	P13	24-Lead (300-Mil) Molded DIP	Commercial
	CY7C197-45VC	V13	24-Lead Molded SOJ	

Package Diagrams

24-Lead (300-Mil) Molded DIP P13/P13A



24-Lead (300-Mil) Molded SOJ V13



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**	107151	09/10/01	SZV	Change from Spec number: 38-00078 to 38-05049